

ADT DICING SAWS

ADT's dicing saws' line offer a variety of capabilities, configurations and levels of automation as well as unique solutions for special materials and applications. The dicing saws range includes automatic saws, fully automatic saws with single and double spindle, as well as special machines for tailored applications.

ADT'S DICING SAWS UNIQUE FEATURES

Advantages

- Low cost of owner ship
- High throughput
- User freindly
- Flexible
- Customization

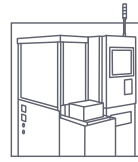
Monitoring

- Temperature monitoring
- Water Flow Monitoring
- Kerf Monitoring
- Product mapping - confocal

Reliability

- Spindle air reservoir
- UPS – Cut Map Saving
- Broken Blade Detector
- Geometric model finder
- Enhanced Kerf check inspection
- Vibration Dampers
- X Air bearing Axis

Quality Standards



Dicing Saws | Fully Automatic

FULLY AUTOMATIC TWIN SPINDLE DICING SAWS

8030

12" Silicon wafer dicing supporting 6" and 8" wafers plus Large QFN multi panels



Features & Benefits

- Up to 76.2mm (3") Blades OD
- Support up to 12" X 12" chuck
- Ionizer Bar – ESD discharge
- BARCODE item identification
- SECS GEM ready

Workpiece Size	Ø 8", Ø 12" or 12" x 12" square	
Spindle	Two facing 1.8 kW or 2.2 kW, max. 60,000 rpm	
Blade Size	2" – 3"	
Y1 / Y2 Axis	Control	Linear encoder for each Y axis
	Resolution	0.1 µm
	Cumulative Accuracy	1.5 µm
	Indexing Accuracy	1.0 µm
X Axis	Indexing Accuracy	1.0 µm
	Cutting Range	350 mm
Z1 / Z2 Axis	X Axis	Air Slide
	Resolution	0.2 µm
	Repeatability	1.0 µm
Ø Axis	Max. Stroke	50 mm (for 2.188" blade OD)
	Repeatability	4 arc-sec
Cleaning Station	Stroke	380°
	Cleaning Station	Full rinse and dry cycle
Utilities	Spinning speed	100-3,000 rpm
	Cleaning Method	Atomized cleaning capabilities
Dimensions	Electrical	200-240 VAC, 50/60 Hz, single phase
	(W x D x H) mm	1145 x 1687 x 1830
	Weight	1,500kg

Materials:

Silicon wafers | Thin Glass | QFN and BGA multi pannels